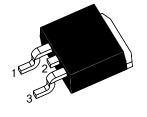
N-Channel Enhancement Mode MOSFET

Features

- AEC-Q101 Qualified
- · Advanced trench cell design
- · High speed switch
- Halogen and Antimony Free(HAF), RoHS compliant

Drain Gate Source



1.Gate 2.Drain 3.Source TO-263 Plastic Package

Applications

- Portable appliances
- Power management

Kev Parameters

Parameter	Value	Unit		
BV _{DSS}	60	V		
R _{DS(ON)} Max	3.2 @ V _{GS} = 10 V	mΩ		
V _{GS(th)} typ	3.0	V		
Qg typ	75 @ V _{GS} = 10 V	nC		

Absolute Maximum Ratings (at T_a = 25°C unless otherwise specified)

Parameter	Symbol	Value	Unit	
Drain-Source Voltage	V _{DS}	60	V	
Drain-Gate Voltage	V_{GS}	± 20	V	
Drain Current - Continuous $T_c = T_c = T_c$		I _D	120 77	Α
Drain Current - Pulsed 1)	I _{DM}	480	А	
Avalanche Current, Single Pulse	I _{AS}	44.8	Α	
Avalanche Energy, Single Pulse 2)	E _{AS}	100.3	mJ	
Power Dissipation	P _D	62.5	W	
Operating Junction and Storage Temperature	T_{j}, T_{stg}	- 55 to + 150	°C	

Thermal Characteristics

Parameter	Symbol	Max.	Unit
Thermal Resistance from Junction to Case	R ₀ JC	2	°C/W
Thermal Resistance from Junction to Ambient 3)	Reja	40	°C/W

 $^{^{1)}}$ Pulse Test: Pulse Width ≤ 100 μs, Duty Cycle ≤ 2%, Repetitive rating, pulse width limited by junction temperature $T_{J(MAX)}$ = 150°C.



 $^{^{2)}}$ Limited by $T_{J(MAX)},$ starting T_J = 25 °C, L = 0.1 mH, R_g = 25 $\Omega,$ I_D = 44.8 A, V_{GS} = 10 V.

³⁾ Device mounted on FR-4 substrate PC board, 2oz copper, with 1-inch square copper plate in still air.

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Characteristics at T_a = 25°C unless otherwise specified

Parameter	Symbol	Min.	Тур.	Max.	Unit
STATIC PARAMETERS			•		
Drain-Source Breakdown Voltage at I _D = 1 mA	BV _{DSS}	60	-	-	V
Drain-Source Leakage Current at V _{DS} = 60 V	IDSS	-	-	1	μΑ
Gate-Source Leakage Current at $V_{GS} = \pm 20 \text{ V}$	lgss	-	-	± 100	nA
Gate-Source Threshold Voltage at V_{DS} = V_{GS} , I_D = 120 μ A	V _{GSth}	2	-	4	V
Drain-Source On-State Resistance at V_{GS} = 10 V, I_D = 100 A	R _{DS(on)}	-	2.8	3.2	mΩ
DYNAMIC PARAMETERS					
Gate resistance at V _{DS} = 0 V, f = 1 MHz	Rg	-	1.1	-	Ω
Input Capacitance at $V_{GS} = 0 \text{ V}$, $V_{DS} = 25 \text{ V}$, $f = 1 \text{ MHz}$	C _{iss}		4597	-	pF
Output Capacitance at V_{GS} = 0 V, V_{DS} = 25 V, f = 1 MHz	Coss	-	2133	-	pF
Reverse Transfer Capacitance at V _{GS} = 0 V, V _{DS} = 25 V, f = 1 MHz	C _{rss}	-	110	-	pF
Total Gate Charge at V_{DS} = 30 V, I_D = 25 A, V_{GS} = 10 V	Qg	-	75	-	nC
Gate Source Charge at V_{DS} = 30 V, I_D = 25 A, V_{GS} = 10 V	Q _{gs}	-	23	-	nC
Gate Drain Charge at V_{DS} = 30 V, I_D = 25 A, V_{GS} = 10 V	Q_{gd}	-	22	-	nC
Turn-On Delay Time at V_{DS} = 30 V, V_{GS} = 10 V, I_D = 25 A , R_g = 4.7 Ω , R_L = 1.2 Ω	t _{d(on)}	-	39	-	nS
Turn-On Rise Time at V_{DS} = 30 V, V_{GS} = 10 V, I_D = 25 A , R_g = 4.7 Ω , R_L = 1.2 Ω	t _r	-	69	-	nS
Turn-Off Delay Time at V_{DS} = 30 V, V_{GS} = 10 V, I_D = 25 A , R_g = 4.7 Ω , R_L = 1.2 Ω	T _{d(off)}	-	27	-	nS
Turn-Off Fall Time at V_{DS} = 30 V, V_{GS} = 10 V, I_D = 25 A , R_g = 4.7 Ω , R_L = 1.2 Ω	t _f	-	9	-	nS
Body-Diode PARAMETERS					
Drain-Source Diode Forward Voltage at $I_S = 100 \text{ A}$, $V_{GS} = 0 \text{ V}$	V _{SD}	-	-	1.3	V
Body-Diode Continuous Current	Is	-	-	120	Α
Body-Diode Continuous Current, Pulsed	I _{SM}	-	-	480	Α
Body Diode Reverse Recovery Time at Is = 25 A, di/dt = 100 A / μ s	t _{rr}	-	44	-	nS
Body Diode Reverse Recovery Charge at I_S = 25 A, di/dt = 100 A / μs	Qrr	-	40	-	nC



Electrical Characteristics Curves

ii Cilaracteristics Curves

Fig. 1 Typical Output Characteristic

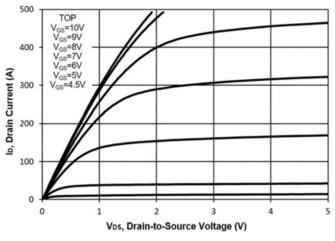


Fig. 2 Typical Transfer Characteristic

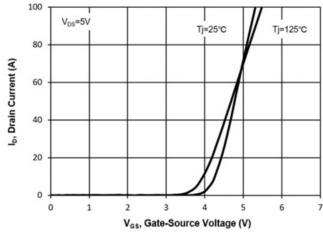


Fig. 3 on-Resistance vs. Drain Current

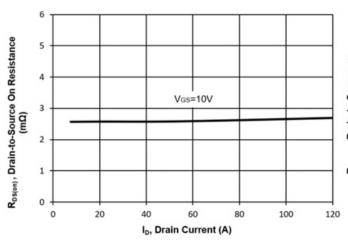


Fig. 4 on-Resistance vs. Gate Voltage

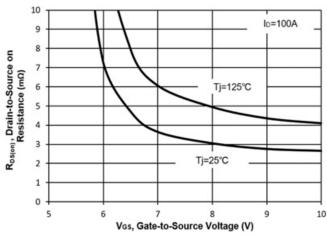


Fig. 5 on-Resistance vs.T_j

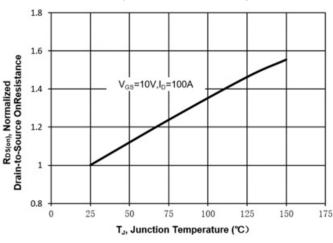
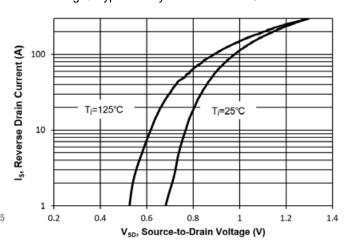


Fig. 6 Typical Body-Diode Forward Characteristic





Electrical Characteristics Curves

Fig. 7 Typical Junction Capacitance

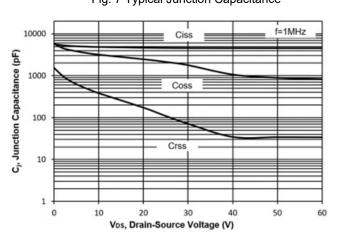


Fig. 8 Drain-Source Leakage Current vs. Ti

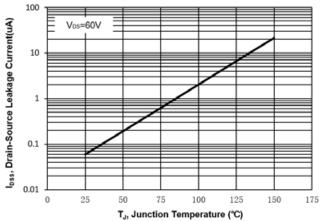


Fig. 9 V_{(BR)DSS} vs. Junction Temperature

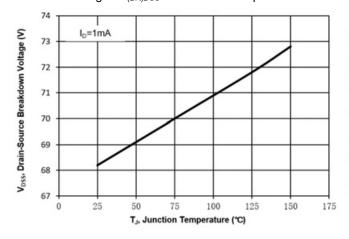


Fig. 10 Gate Threshold Variation vs. T_j

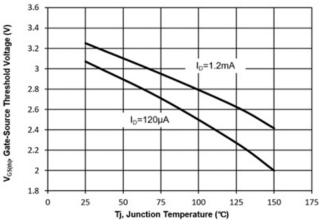


Fig. 11 Gate Charge

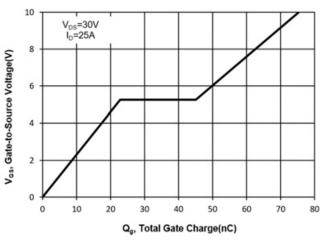
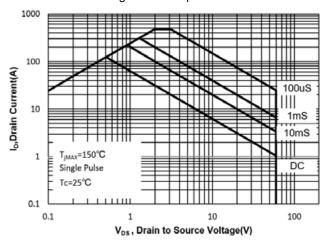


Fig. 12 Safe Operation Area





Electrical Characteristics Curves

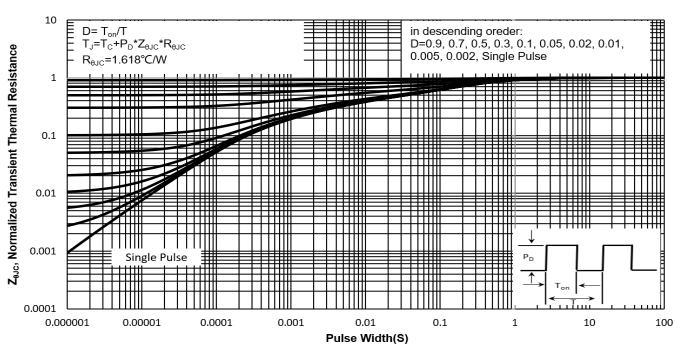
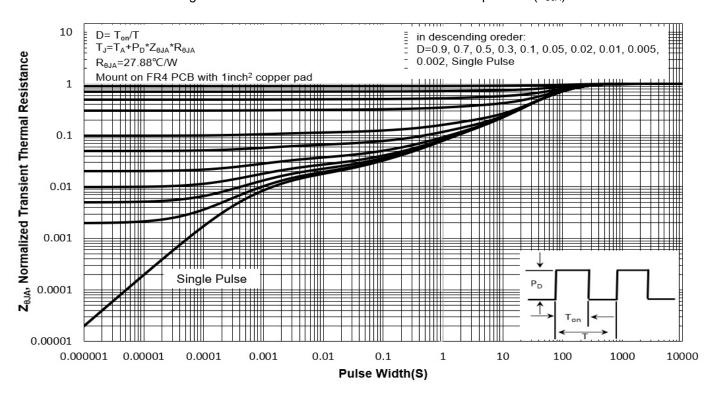


Fig. 13 Normalized Maximum Transient Thermal Impedance(zeuc)

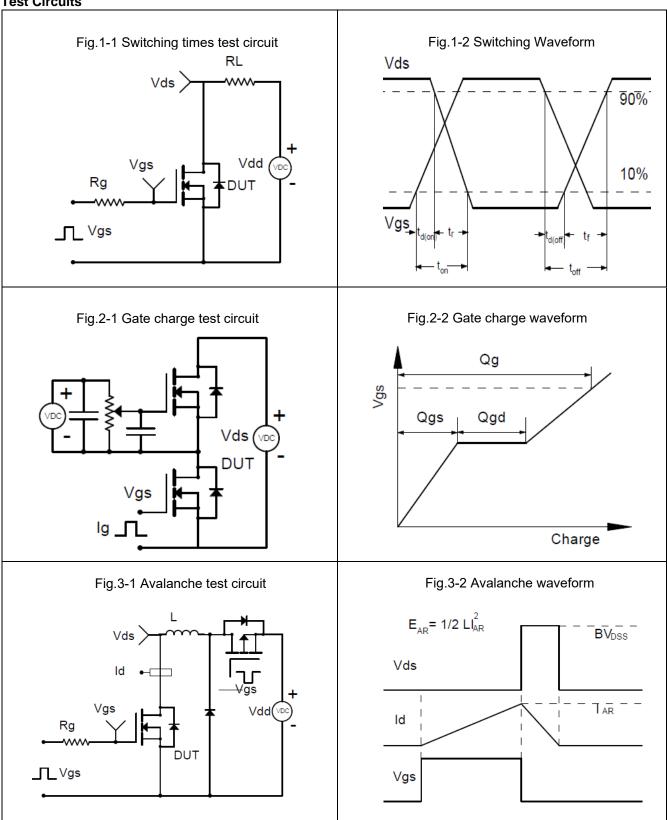






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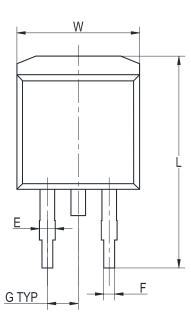
Test Circuits

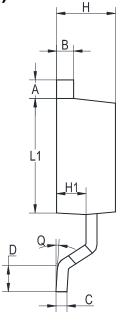


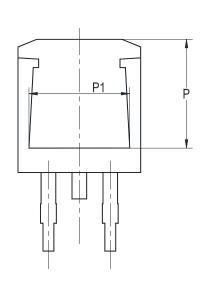


Package Outline (Dimensions in mm)

TO-263

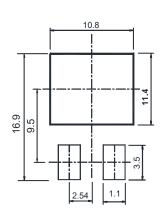






UNIT	Α	В	С	D	E	F	G	W	Н	H1	L	L1	Q	Р	P1
	1.5	1.5	0.5	2.60	1.6	0.94	2.54	10.5	4.8	2.9	16.5	8.7	8°	7.6	8.2
mm	1.1	1.1	0.3	2.15	1.1	0.68	TYP	9.6	4.4	2.5	14.5	8.2	MAX	7.1	7.4

Recommended Soldering Footprint



Packing information

Package	Carton Quantity	Box Quantity	Base Quantity	Delivery Mode
TO-263	5 K / Carton	1 K / Box	50 pcs / Tube	Tube

Marking information

" TV06N028S" = Part No.

" ***** " = Date Code Marking

Font type: Arial





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